

# HVD396C

## Variable Capacitance Diode for VCO

REJ03G0213-0100Z

(Previous: ADE-208-1511)

Rev.1.00 Jun 07, 2004

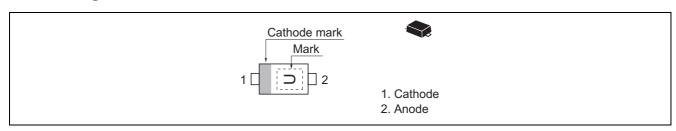
#### **Features**

- High capacitance ratio. (n = 2.62 min)
- Low series resistance. (rs =  $0.40 \Omega \text{ max}$ )
- Super small Flat Package (SFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Laser Mark	Package Code
HVD396C	U	SFP

## **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

### **Electrical Characteristics**

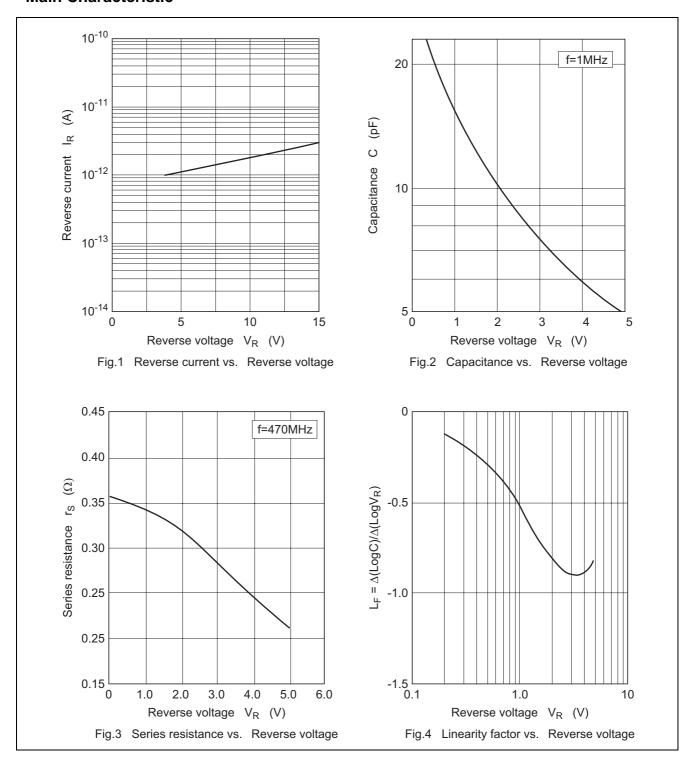
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R1</sub>	_	_	10	nA	V <sub>R</sub> = 10 V
	I <sub>R2</sub>	_	_	50		V <sub>R</sub> = 10 V, Ta = 60°C
Capacitance	C <sub>1</sub>	14.6	_	15.8	pF	V <sub>R</sub> = 1 V, f = 1 MHz
	C <sub>4</sub>	5.20	_	5.80		$V_R = 4 \text{ V}, f = 1 \text{ MHz}$
Capacitance ratio	n	2.62	_	_	_	C <sub>1</sub> / C <sub>4</sub>
Series resistance	r <sub>S</sub>	_	_	0.40	Ω	V <sub>R</sub> = 1 V, f = 470 MHz

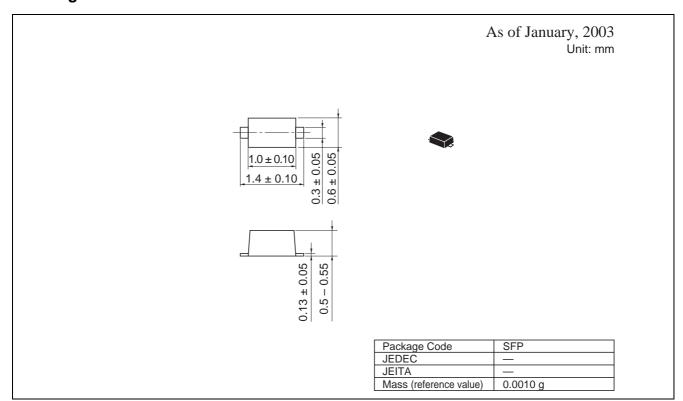
Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

<sup>2.</sup> The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

### **Main Characteristic**



## **Package Dimensions**



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